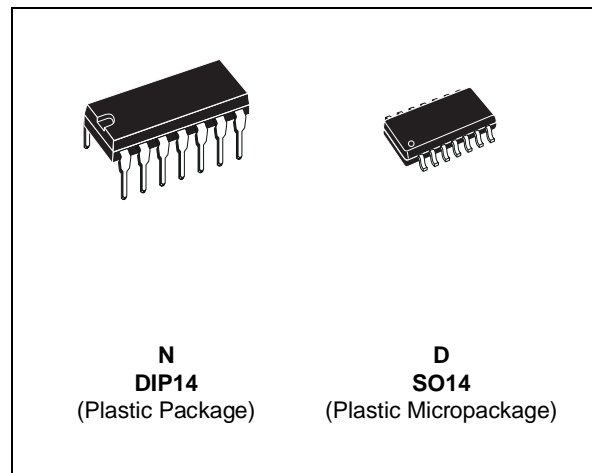




15V TRIPLE IGBT/MOS DRIVER

- THREE POWER IGBT/MOS OR PULSE TRANSFORMER DRIVERS
- CURRENT SENSE COMPARATOR WITH 1ms INHIBITION TIME FUNCTION
- INSTANTANEOUS SIGNAL TRANSMISSION
- 0.6 Amp PER CHANNEL PEAK OUTPUT CURRENT CAPABILITY
- LOW OUTPUT IMPEDANCE TYP : 7Ω at 200mA
- CMOS/LSTTL COMPATIBLE INVERTING INPUT WITH HYSTERESIS
- 13V TO 16V SINGLE SUPPLY OPERATION
- UNDER VOLTAGE LOCKOUT (12.5V)
- CURRENT AMPLIFIER
- LOW BIAS CURRENT TYP : 1.5mA
- DURING POWER UP NO RANDOM OUTPUT STATE
- ENHANCED LATCH-UP IMMUNITY
- CHANNEL PARALLELING CAPABILITY



ORDER CODES

Part Number	Temperature Range	Package	
		N	D
TD300I	-40°C, +105°C	•	•

DESCRIPTION

The TD300 is designed to drive one, two or three Power IGBT/MOS and has driving capability for pulse transformer. So it is perfectly suited to interface control IC with Power Switches in low side or half-bridge configuration.

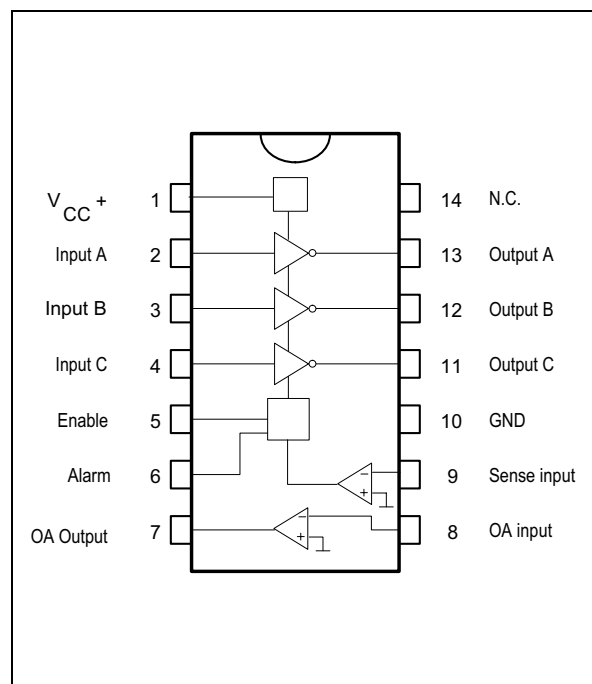
The typical application shown figure 1 implements the TD300 in a pulse controlled half-bridge drive. Positive and negative pulses are applied to the pulse transformer to charge and discharge the IGBT/MOS gate capacitance. More sophisticated secondary circuits provide low impedance gate drive and short-circuit protection as shown in application note AN461.

On Figure 2, TD300 is implemented as a low side driver in a typical 3 phase motor drive.

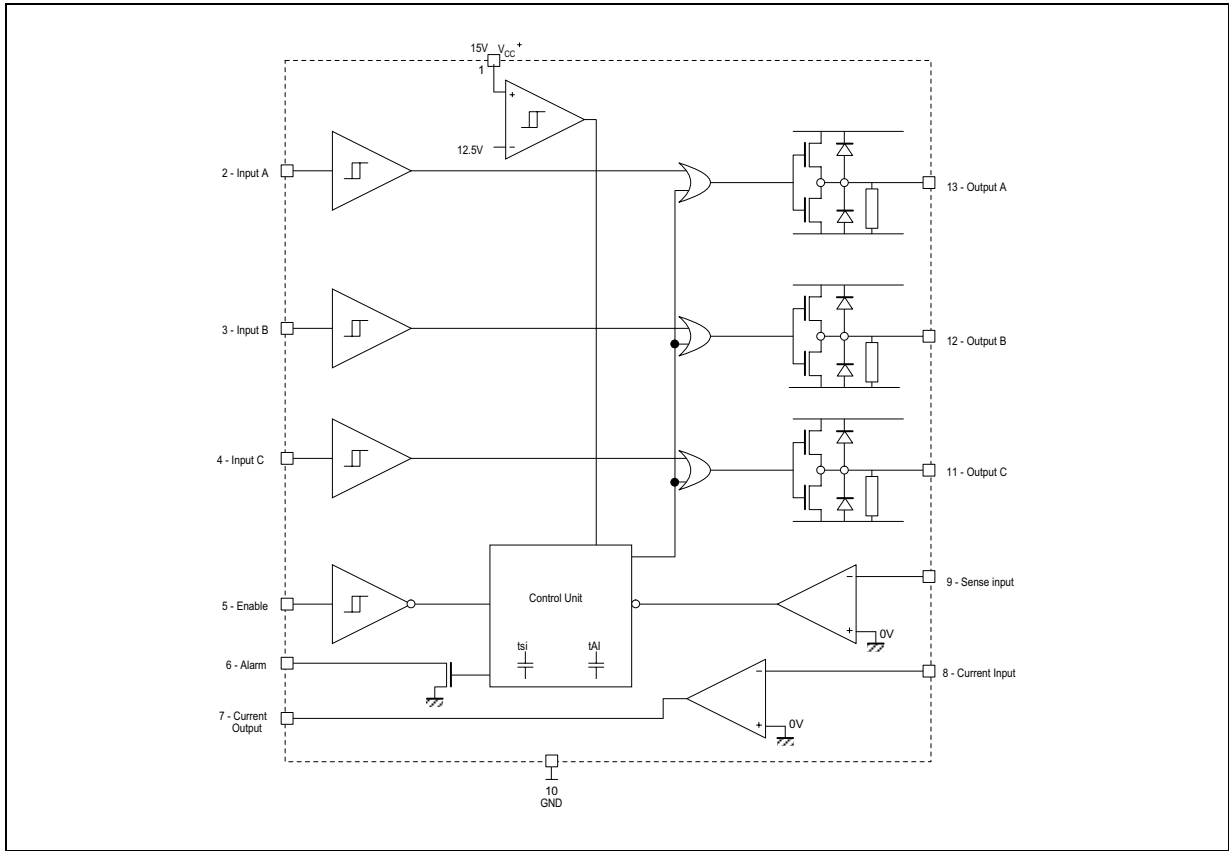
Figure 3 presents a general purpose low side gate drive.

In both case, the current amplifier provides interfacing between a sense resistor and an A/D converter.

PIN CONNECTIONS



BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage	18	V
V _i	Input Voltage	0 to V _{CC}	V
V _{is}	Sense Input Voltage	-0.3 to V _{CC}	V
T _j	Operating Junction Temperature	-40 to 150	°C
T _{amb}	Operating Ambient Temperature	-40 to 105	°C
T _{stg}	Storage Temperature Range	-65 to 150	°C

OPERATING CONDITIONS

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage	13 to 16	V

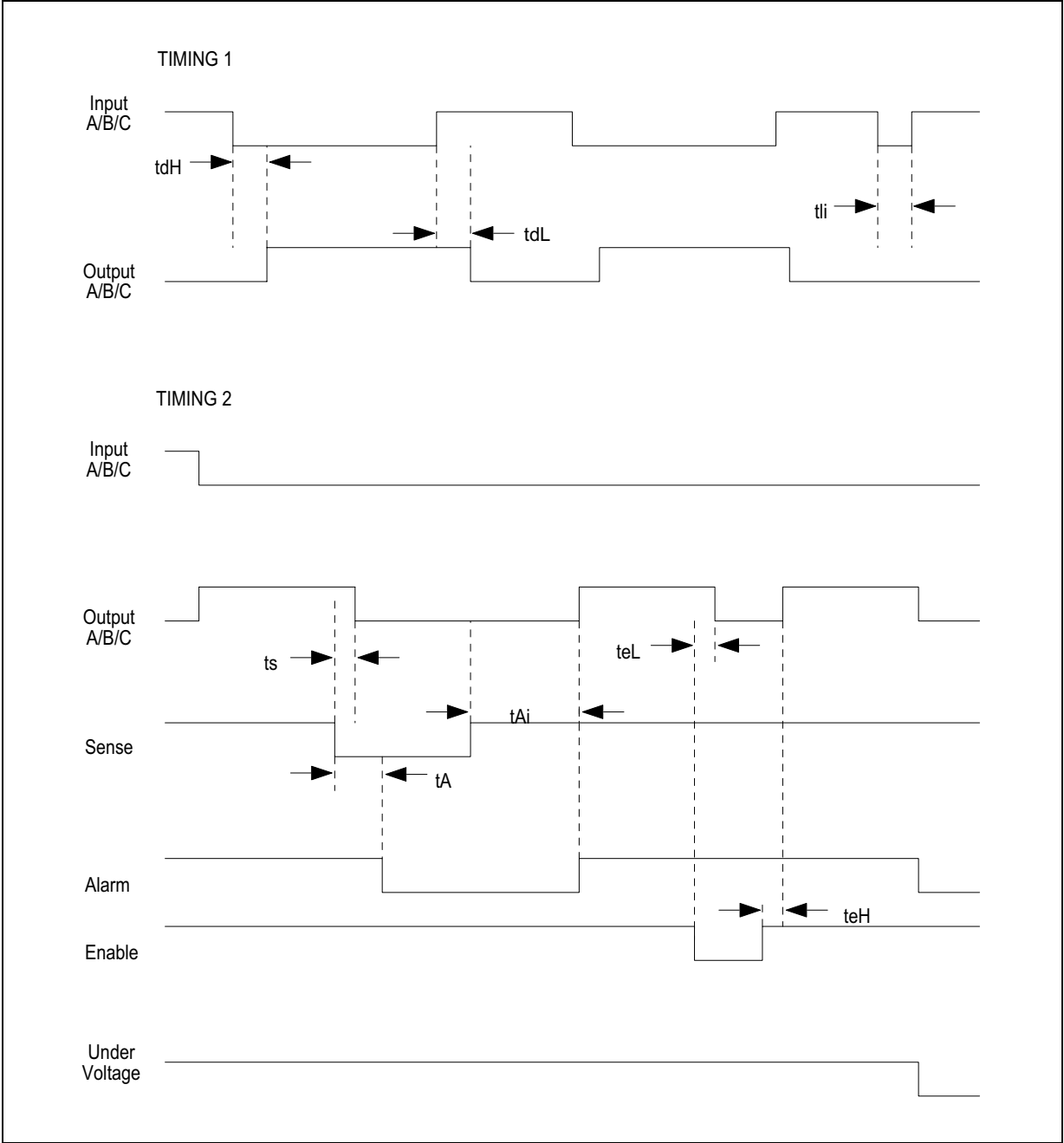
INSTRUCTIONS FOR USE

- 1 - The TD300 supply voltage must be decoupled with a 1µF min. capacitor.
- 2 - If the application involving TD300 requires maximum output current capability, this current must be pulsed : pulse width 1µsec, duty cycle 1% at T_{amb}.

ELECTRICAL CHARACTERISTICSV_{CC} = 15V, T_{amb} = 25°C (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
I _{CC}	Supply Current with Inputs in High State		1.5	2	mA
LOGIC INPUT (all inputs)					
V _{IH}	High Input Voltage	2			V
V _{IL}	Low Input Voltage			0.8	V
I _{IH}	High Input Current		10		pA
I _{IL}	Low Input Current		10		pA
t _{dH,t_{eL}} t _{dL,t_{eH}}	Propagation Delay (10% input to 10% output) Output Delay Output Delay T _{min.} ≤ T _{amb} ≤ T _{max.}		200 60	400 400	ns
t _{ij}	Input Inhibiting Time		100		ns
t _{dd}	Differential Delay Time Between Channels		20		ns
OUTPUT DRIVERS					
V _{sod}	Sourcing Drop Voltage (A/B/C outputs) I _{source} = 200mA			3	V
V _{sid}	Sinking Drop Voltage (A/B/C outputs) I _{sink} = 200mA			5	V
V _{dem}	Demagnetising Drop Voltage (A/B/C outputs) I _{demag.} = 100mA			2	V
R _{opd}	Output Pull Down Resistor		47		kΩ
UNDERVOLTAGE LOCKOUT					
V _{hys}	Threshold Hysteresis		0.8		V
V _{st}	Internal Start Threshold	11.7		13.3	V
ALARM OUTPUT					
I _s	Low Level Sinking Current V _O = 0.8V	5	35		mA
I _{sh}	High Level Sinking Current			500	nA
t _A	Alarm Output : Delay Time to Alarm Fall if Sense Input Triggered			500	ns
SENSE INPUT					
V _{ios}	Input Offset Voltage			20	mV
t _{Ai}	Inhibition Time if Sense Input Triggered		1		ms
t _s	Delay Time to Output Fall if Sense Input Triggered All outputs inhibited			600	ns
t _{si}	Inhibition Time of Sense Input		300		ns
V _{shys}	Sense Hysteresis		40		mV
OPERATIONAL AMPLIFIER					
V _{icm}	Common Mode Input Voltage Range	0 to V _{CC} ⁺ - 1.5			V
V _{io}	Input Offset Voltage			10	mV
I _{io}	Input Offset Current		1		pA
I _o	Output Short Circuit Current (V _{id} = 100mV, V _o = 0V)		60		mA
V _{OL}	Low Level Output Voltage (V _{id} = -100mV)		20		mV
V _{OH}	High Level Output Voltage (V _{id} = 100mV, R _L = 100kΩ)		8.9		V
GBP	Gain Bandwidth Product		1		MHz
A _{vd}	Open Loop Gain	60			dB
SR	Slew Rate at Unity Gain (R _L = 100kΩ, C _L = 100pF, V _i = 3 to 7V)		0.6		V/μs

TIMING DIAGRAM



TYPICAL APPLICATIONS

Figure 1 : THREE PHASE MOTOR HIGH AND LOW SIDE DRIVE

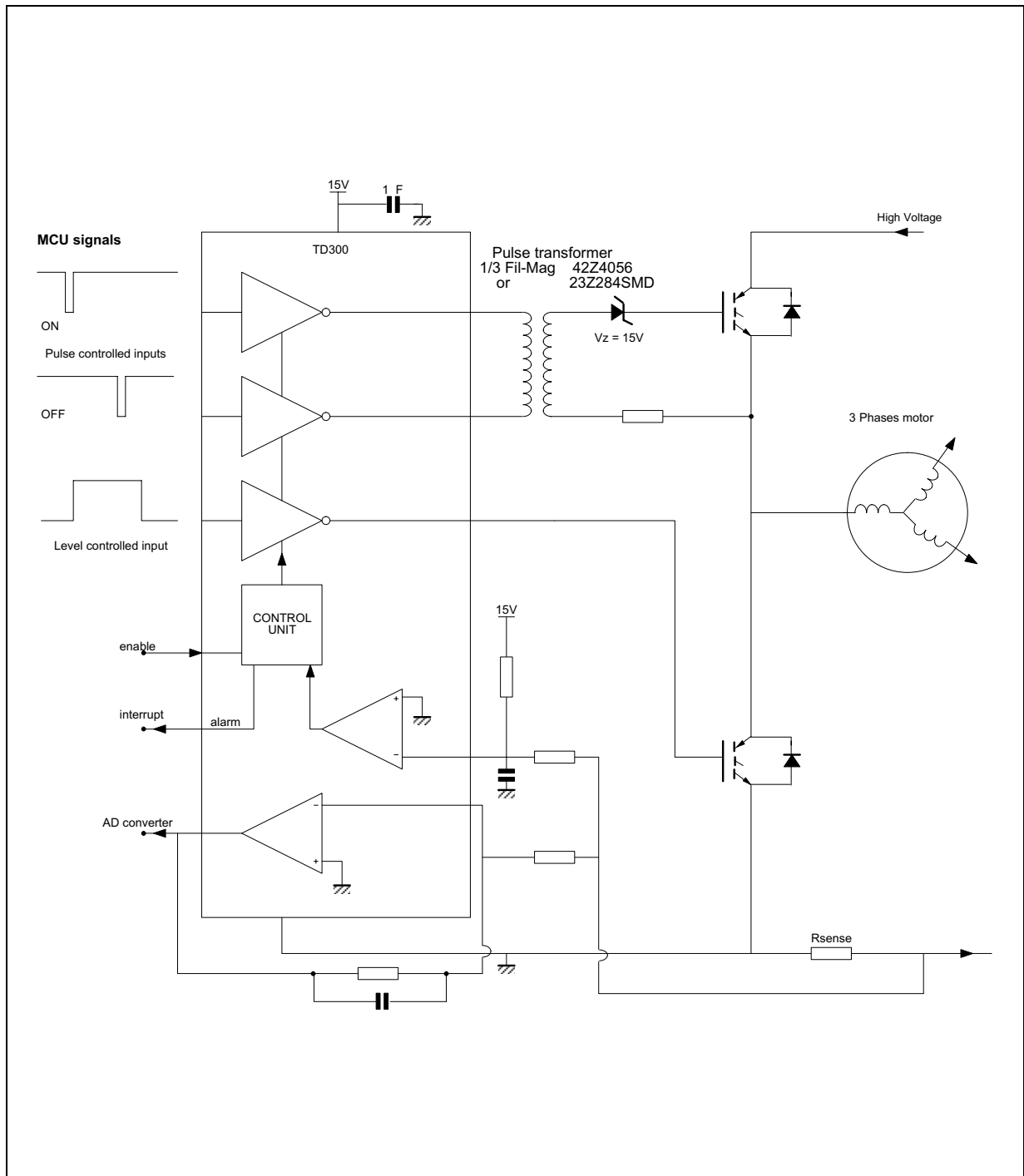


Figure 2 : THREE PHASE MOTOR LOW SIDE DRIVE

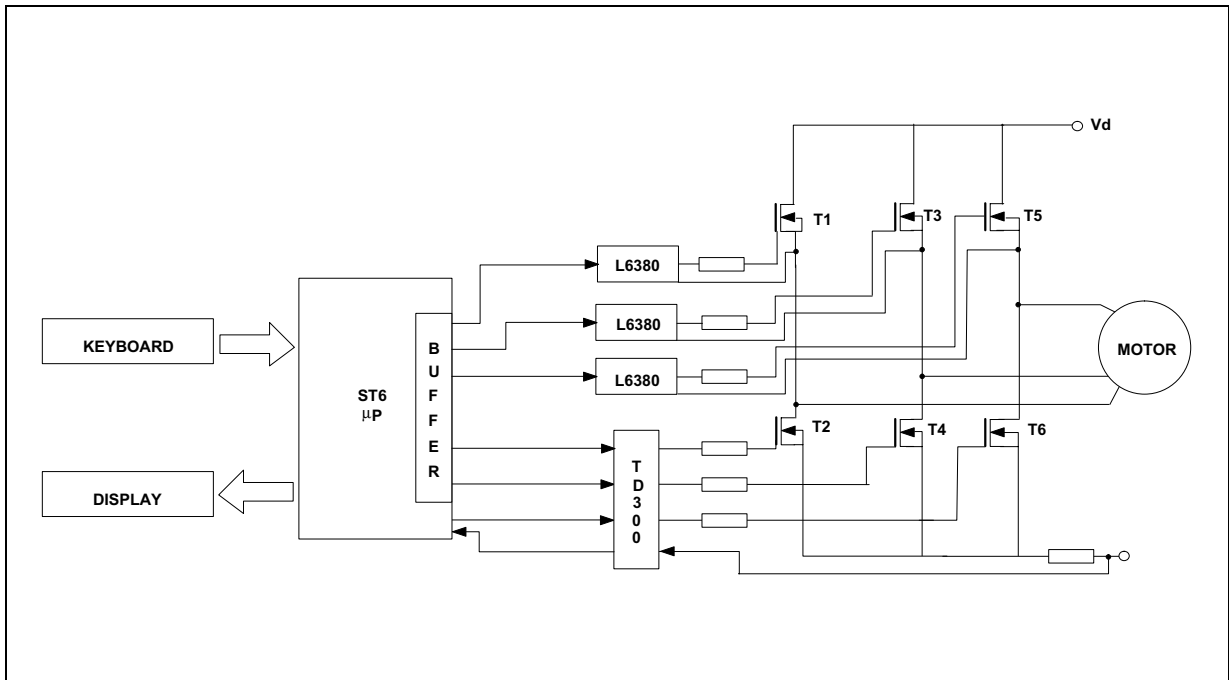
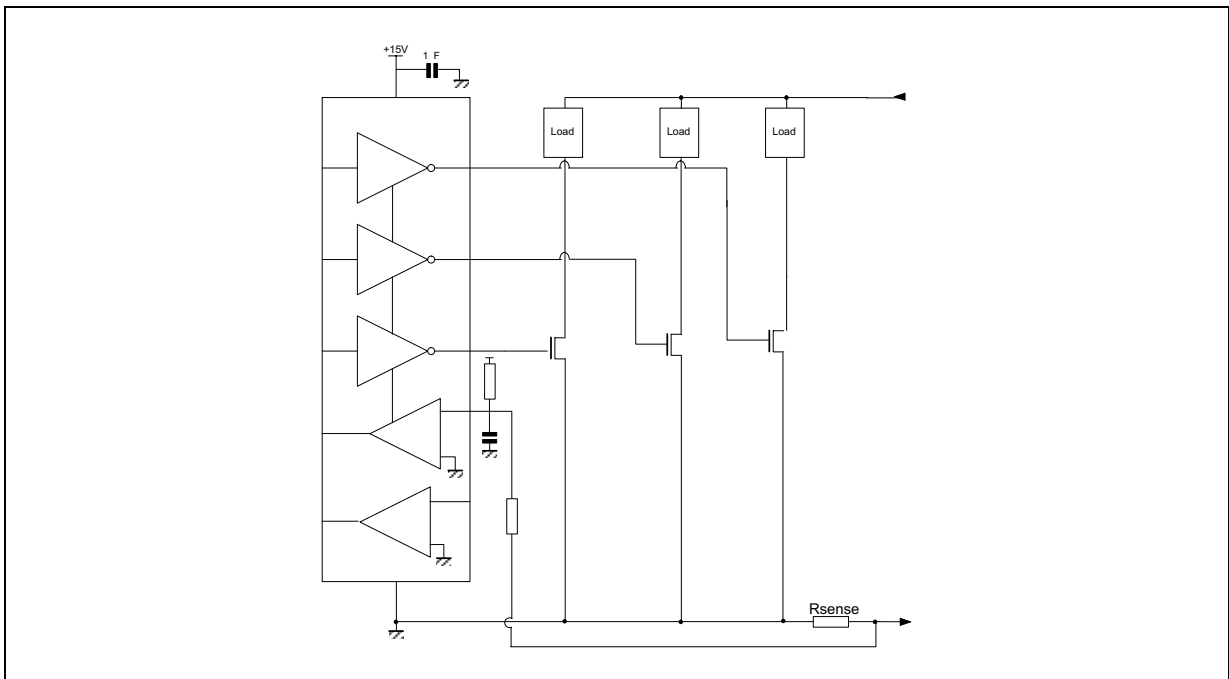
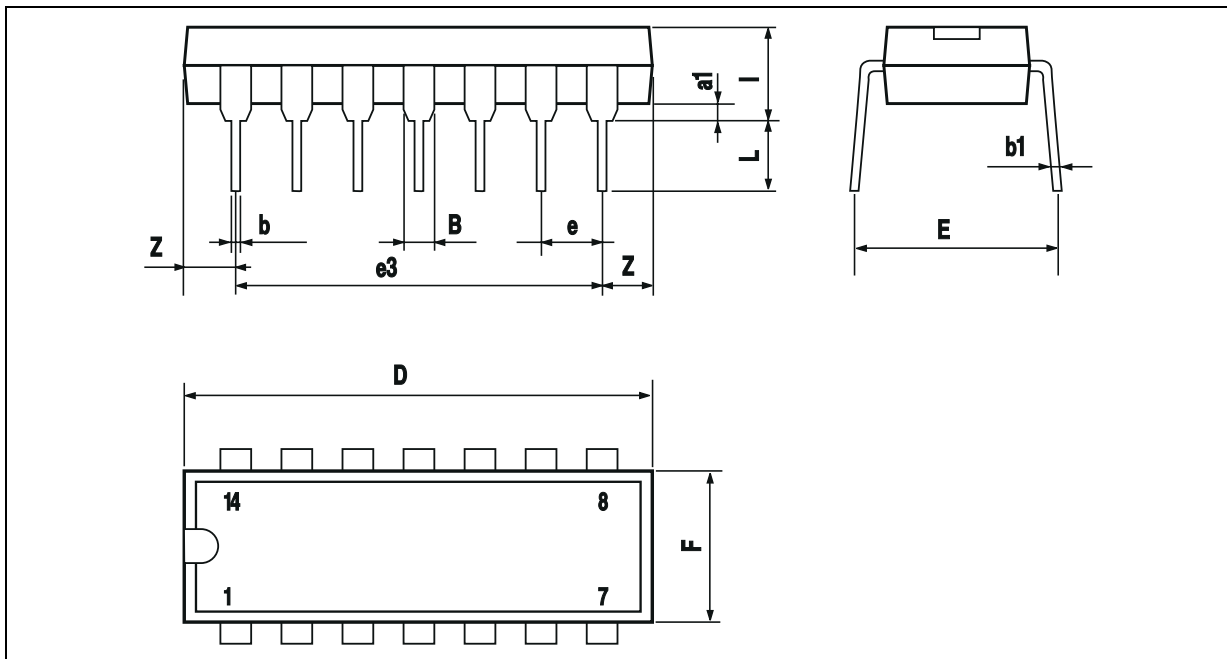


Figure 3 : LOW SIDE DRIVE

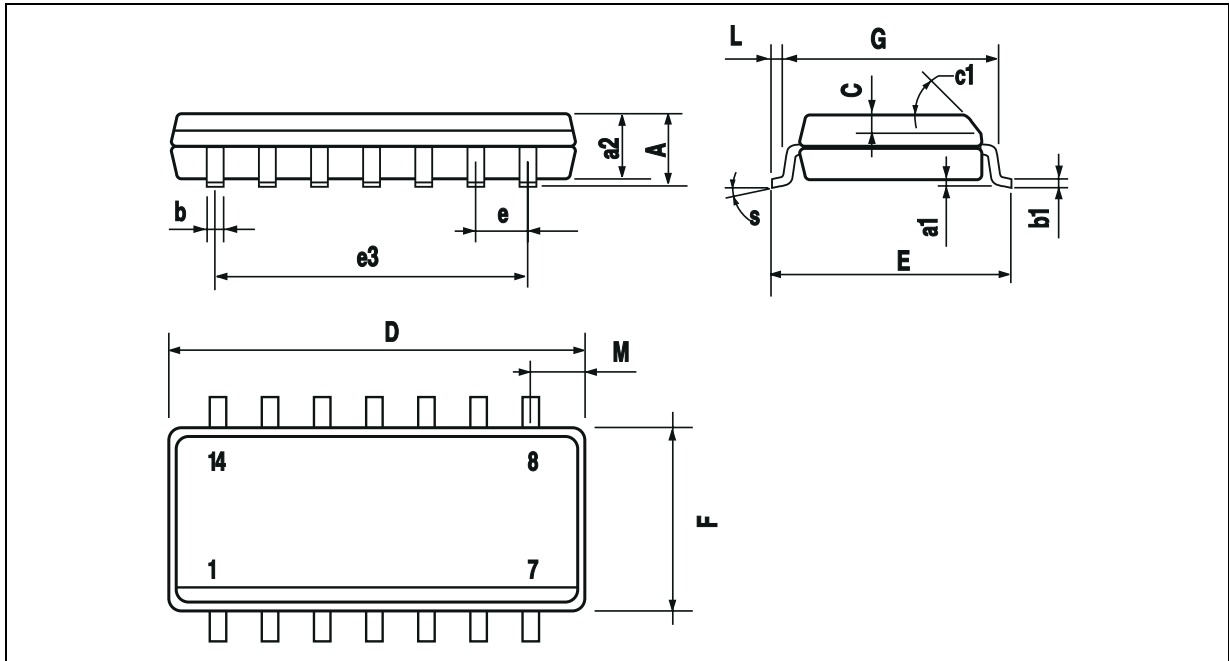


PACKAGE MECHANICAL DATA
14 PINS - PLASTIC DIP



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
a1	0.51			0.020		
B	1.39		1.65	0.055		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		15.24			0.600	
F			7.1			0.280
i			5.1			0.201
L		3.3			0.130	
Z	1.27		2.54	0.050		0.100

PACKAGE MECHANICAL DATA
14 PINS - PLASTIC MICROPACKAGE (SO)



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
a1	0.1		0.2	0.004		0.008
a2			1.6			0.063
b	0.35		0.46	0.014		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.020	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.334
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.150		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.020		0.050
M			0.68			0.027
S	8° (max.)					

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